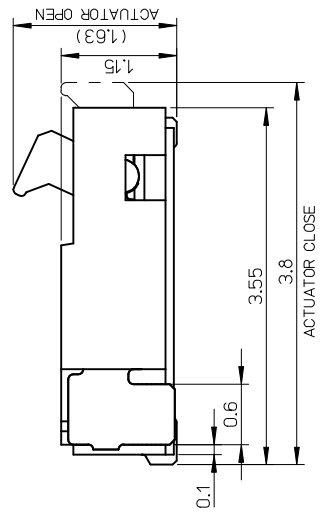
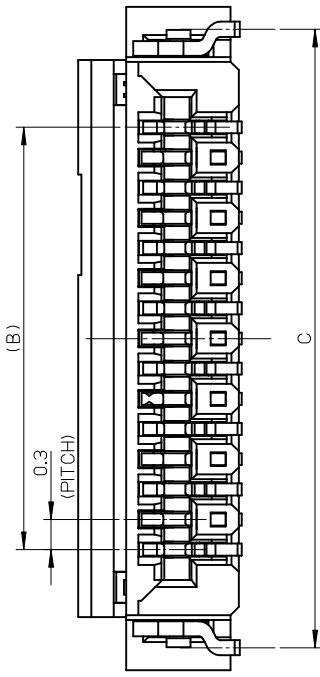


断面図



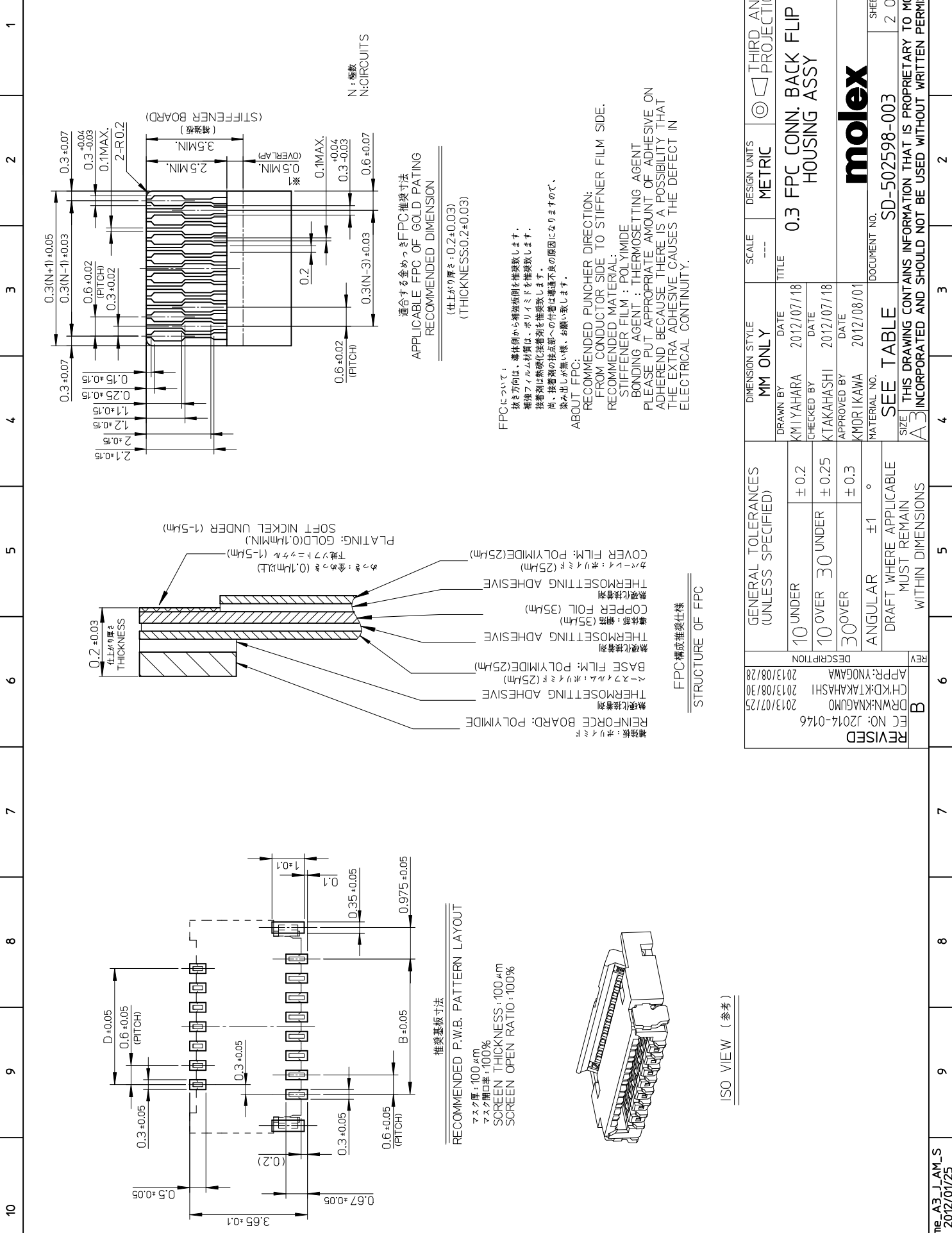
注記 NOTES:

- 1.材質 MATERIAL  
ハウジング: LCP(液晶ポリマー)、白色、ガラス充填、UL94V-0  
HOUSING: LIQUID CRYSTAL POLYMER, WHITE (NATURAL)  
GLASS FILLED, UL94V-0  
アクチュエータ: ポリアミド樹脂  
黒色、ガラス充填、UL94HB  
ACTUATOR: POLYAMIDE  
BLACK GLASS FILLED, UL94HB  
ターミナル: 焼青銅 (t=0.12)  
TERMINAL: PHOSPHOR BRONZE (t=0.12)  
金具: 焼青銅 (t=0.15)  
NAIL: PHOSPHOR BRONZE (t=0.15)  
2.めっき仕様 PLATING  
ターミナル TERMINAL  
接点部: 金めっき 0.1μm以上  
CONTACT AREA: GOLD 0.1 MICROMETER MINIMUM  
半田付け部: 金めっき  
SOLDER TAIL AREA: GOLD  
下地めっき: ニッケル 1.0μm以上  
UNDER PLATING: NICKEL 1.0 MICROMETER MINIMUM  
金具 NAIL  
めっき 1.0μm以上  
TIN PLATING 1.0 MICROMETER MINIMUM  
下地めっき: ニッケル 1.0μm以上  
UNDER PLATING: NICKEL 1.0 MICROMETER MINIMUM  
3.平坦度は、0.1ミリ以下とする。  
TAILS COPLANARITY TO BE 0.1 MAXIMUM.  
4.ELV及びRoHS適合品  
ELV AND RoHS COMPLIANT  
5.本製品は502598-\*\*-91の端子材料製品である。  
THIS PRODUCT IS CHANGE OF TERMINAL MATERIAL  
FOR 502598-\*\*-91.

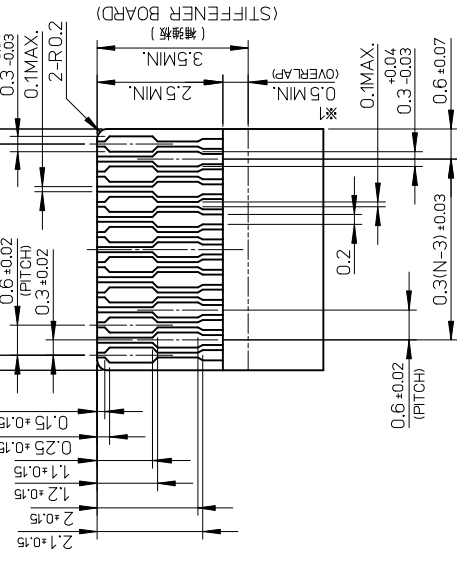
0.125	14.4	16.95	15	17.4	502598-5193	51
0.112	12.6	15.15	13.2	15.6	502598-4593	45
0.105	11.4	13.95	12.0	14.4	502598-4193	41
0.098	10.8	13.35	11.4	13.8	502598-3993	39
0.085	9	11.55	9.6	12	502598-3393	33
0.077	7.8	10.35	8.4	10.8	502598-2993	29
0.072	7.2	9.75	7.8	10.2	502598-2793	27
0.068	6.6	9.15	7.2	9.6	502598-2593	25
0.063	6	8.55	6.6	9	502598-2393	23
0.048	4.2	6.75	4.8	7.2	502598-1793	17
0.043	3.6	6.15	4.2	6.6	502598-1593	15
重さ (g)	D	C	B	A	EMBOSSED PACKAGE オーダー番号	極数
WEIGHT(g)	D	C	B	A	ORDER NO.	CIRCUITS

DIMENSION STYLE		CONNECTOR SERIES NO.	
MM ONLY	SCALE	502598-**-21	DESIGN UNITS
GENERAL TOLERANCES (UNLESS SPECIFIED)		METRIC	
DRAWN BY		THIRD ANGLE PROJECTION	
KMIYAHARA	DATE	TITLE	
2012/07/18	2012/07/18	0.3 FPC CONN. BACK FLIP HOUSING ASSY	
CHECKED BY	DATE	SHEET NO.	
KTAKAHASHI	2012/07/18	1 OF 2	
APPROVED BY	DATE	DOCUMENT NO.	
KMORIKAWA	2012/08/01	SD-502598-003	
MATERIAL NO.	SEE TABLE		
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			

REVISION	DESCRIPTION	DATE	BY
B	REVISED	2013/07/25	DRWN:KNA/GUMO
	CHG:KTAKAHASHI	2013/08/30	
	APP:YNOGAWA	2013/08/28	

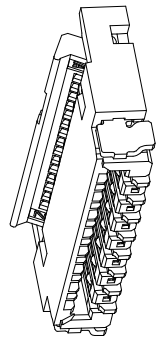


構造: ポリイミド  
 REINFORCE BOARD: POLYIMIDE  
 熱硬化接着剤  
 THERMOSETTING ADHESIVE  
 ベースフィルム: ポリイミド (25µm)  
 BASE FILM: POLYIMIDE (25µm)  
 熱硬化接着剤  
 THERMOSETTING ADHESIVE  
 銅箔: 銅箔 (35µm)  
 COPPER FOIL (35µm)  
 熱硬化接着剤  
 THERMOSETTING ADHESIVE  
 カバート: ポリイミド (25µm)  
 COVER FILM: POLYIMIDE (25µm)  
 めっき: めっき (0.14µm)  
 下地メッキ (1-5µm)  
 PLATING: GOLD (0.14µm MIN.)  
 SOFT NICKEL UNDER (1-5µm)



適合する金めっきFPC推奨寸法  
 APPLICABLE FPC OF GOLD PATING  
 RECOMMENDED DIMENSION  
 (仕上がり厚さ: 0.2±0.03)  
 (THICKNESS: 0.2±0.03)

推奨基板寸法  
 RECOMMENDED P.W.B. PATTERN LAYOUT  
 マスク厚: 100µm  
 マスク開口率: 100%  
 SCREEN THICKNESS: 100µm  
 SCREEN OPEN RATIO: 100%



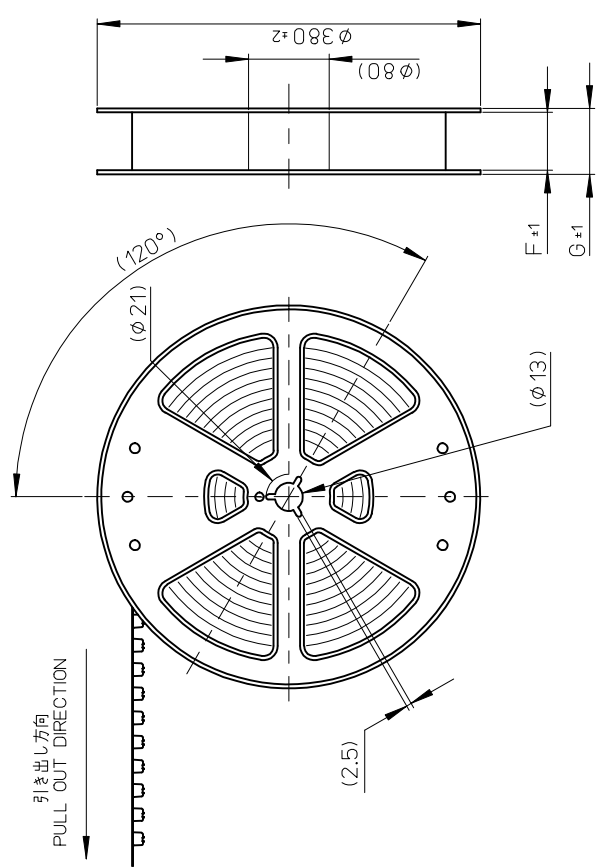
ISO VIEW (参考)

FPCについては:  
 抜き方向は、導体側から増強板側を推奨致します。  
 補強フィルム材質は、ポリイミドを推奨致します。  
 接着剤は熱硬化接着剤を推奨致します。  
 尚、接着剤の接点部への付着は導体不良の原因になりますので、  
 染み出しが無い様、お願い致します。  
 ABOUT FPC:  
 RECOMMENDED PUNCHER DIRECTION:  
 FROM CONDUCTOR SIDE TO STIFFNER FILM SIDE.  
 RECOMMENDED MATERIAL:  
 STIFFENER FILM: POLYIMIDE  
 BONDING AGENT: THERMOSETTING AGENT  
 PLEASE PUT APPROPRIATE AMOUNT OF ADHESIVE ON  
 ADHEREND BECAUSE THERE IS A POSSIBILITY THAT  
 THE EXTRA ADHESIVE CAUSES THE DEFECT IN  
 ELECTRICAL CONTINUITY.

FPC構成推奨仕様  
 STRUCTURE OF FPC

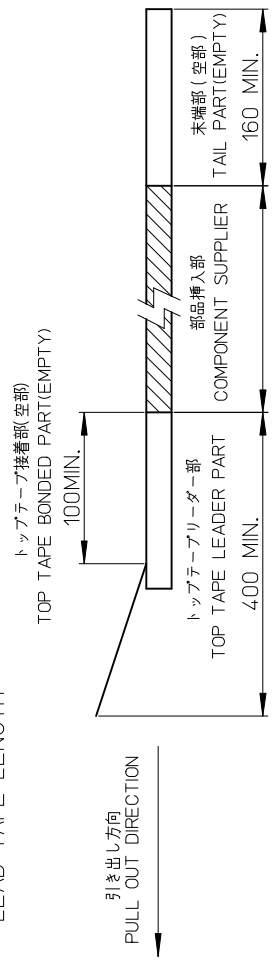
GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
10 UNDER	± 0.2	DRAWN BY KMIYAHARA	DATE 2012/07/18	TITLE 0.3 FPC CONN. BACK FLIP HOUSING ASSY		
10 OVER	30 UNDER	CHECKED BY KITAKAHASHI	DATE 2012/07/18	DOCUMENT NO. SD-502598-003		
30 OVER	ANGULAR ±1°	APPROVED BY KMORIKAWA	DATE 2012/08/01	SHEET NO. 2 OF 2		
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		
REVISED		REVISED		INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		
EC NO: J2014-0146		DRW: KNA/GUMO		MATERIAL NO.		
CHK: K/TAKAHASHI		APP: YNOGAWA		SIZE		
2013/07/25		2013/08/30		A3		
2013/08/28		2013/08/28		A3		

10 9 8 7 6 5 4 3 2 1



注記)  
NOTES

1. 製品番号502598-\*\*21の詳細寸法は、製品単体図面を参照下さい。  
IN THE PACKAGE PART NUMBER 502598-\*\*21 DETAIL DIMENSIONS,  
SEE SALES DRAWING FOR CONNECTOR.
2. 梱包数量：3000個/リール  
NUMBER OF CONNECTORS : 3000 PCS/REEL
3. リードテープ長さ  
LEAD TAPE LENGTH



4. カバーテープの剥離強度については、IEC60286-3に準拠  
COVER TAPE PEEL FORCE IS DEFINED BY IEC 60286-3.

5. 材料

- キャリアテープ：ポリスチレン (PS)  
CARRIER TAPE: POLYSTYRENE (PS)
- トップテープ：ポリエチレンテレフタレート (PET)、他  
TOP TAPE: POLYETHYLENE TEREPHTHALATE (PET), OTHERS
- リール：ポリスチレン (PS)  
REEL: POLYSTYRENE (PS)
- 6. ELV及びRoHS適合品  
ELV AND RoHS COMPLIANT
- 7. 本製品は502598-\*\*91の端子材料変更品である。  
THIS PRODUCT IS CHANGE OF TERMINAL MATERIAL FOR 502598-\*\*91.

GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
10 UNDER	± ---	DRAWN BY KMI YAHARA	DATE 2012/07/18	TITLE 0.3 FPC CONN. BACK FLIP TAPING PACKAGE (502598-**21 SERIES)			
10 OVER	30 UNDER	CHECKED BY KTAKAHASHI	DATE 2012/07/18				
30 OVER	± ---	APPROVED BY KMORI KAWA	DATE 2012/08/01				
ANGULAR	± 1 °	MATERIAL NO. SEE TABLE		DOCUMENT NO. SD-502598-004		SHEET NO. 1 OF 2	
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3					THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION

REVISED	REV
EC NO: J2014-0146	
DRM:KINAGUMO	
CHKD:KTAKAHASHI	
2013/08/30	
APPR:YNOGAWA	
2013/08/28	

